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(54) **ULTRACAPACITOR FOR USE IN A SOLDER REFLOW PROCESS**

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(57) **ABSTRACT**

An ultracapacitor that is capable of exhibiting good properties even after being subjected to high temperatures, such as experienced during solder reflow, is provided. The ultracapacitor contains a housing having sidewalls that extend in a direction generally perpendicular to a base. An interior cavity is defined between an inner surface of the base and the sidewalls within which an electrode assembly can be positioned. To attach the electrode assembly, first and second conductive members are disposed on the inner surface of the base. The electrode assembly likewise contains first and second leads that extend outwardly therefrom and are electrically connected to the first and second conductive members, respectively. The first and second conductive members are, in turn, electrically connected to first and second external terminations, respectively, which are provided on an outer surface of the base.